

S83	2	("6271792").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 18:59
S84	130	dielectric and ((adhesive melt\$4 near layer) and (radiat\$4 antenna) and antenna and patch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/03 20:05
S85	9	("5115217"   "5155493"   "5227749"   "5444453"   "5497164"   "5583376"   "5661494"   "5712644"   "5825334").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/03 19:50
S86	102	dielectric and ((adhesive melt\$4 near layer) and (radiat\$4 antenna) and antenna and patch and ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/03 20:09
S87	182	dielectric and ((adhesive melt\$4 bond\$3 near layer) and (radiat\$4 antenna) and antenna and patch and ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/03 20:10
S88	182	dielectric and ((adhesive melt\$4 bond\$3 near layer) and ((radiat\$4 adj3 element) antenna) and antenna and patch and ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/03 20:10
S89	113	dielectric and ((adhesive melt\$4 bond\$3 near layer) and ((radiat\$4 adj3 element) antenna) and (antenna near3 patch\$3) and ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/03 20:10
S90	11	("4790968"   "5112726"   "5538789"   "5541366"   "5733639"   "5910354"   "6197407"   "6356245"   "6366259"   "6451441"   "6518514").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/04 15:51
S91	491	(343/705).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/04 16:53
S92	164	S91 and ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 15:52

S93	1	S91 and ground and dielectric and ((adhesive melt\$4 bond\$3) near layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 16:02
S94	1	S91 and ground and (dielectric substrate) and ((adhesive melt\$4 bond\$3) near layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 16:17
S95	1	S91 and ground and (dielectric substrate) and ((adhesive adhesiv\$3 melt\$4 bond\$3) near layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 16:17
S96	20	S91 and ground and (dielectric substrate) and (adhesive adhesiv\$3 melt\$4 bond\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 16:54
S97	81	S91 and ground and (dielectric substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 11:28
S98	2	("6703114").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/05 13:51
S99	2	("6271792").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/05 13:51